

PF-709WB WAFER BUMPING PASTE FLUX

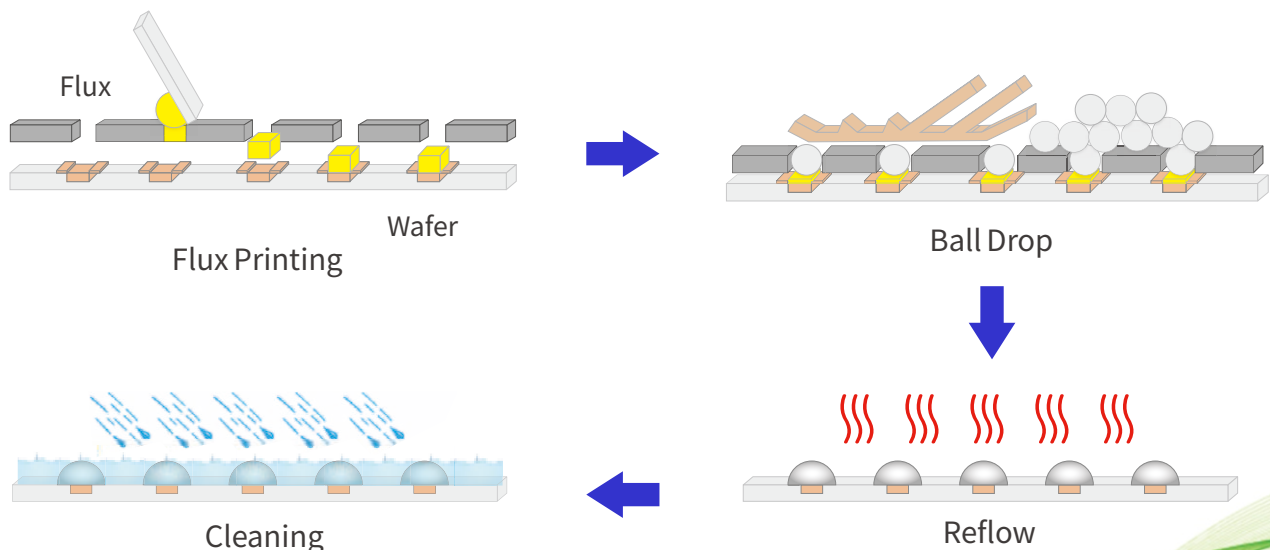
PF-709WB Halogen-Free, Water-Soluble Wafer Bumping paste flux formulation is a mixture of organic acids, thixotropic thickeners and surfactants which aid removal of residues during cleaning. The fluxing activity of this flux is comparable to halogen/halide containing paste fluxes. This flux has been designed for printing application to deliver an optimum amount of paste flux onto the wafer. The high tackiness property provides an excellent attachment of solder spheres onto wafer during ball drop and ensures they are held in place during subsequent process steps. This flux is virtually free of air entrapment, resulting in consistent paste flux deposition.

Main Features



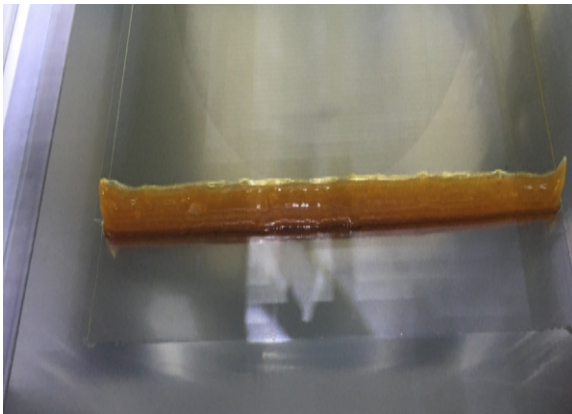
Application

- Wafer Bumping

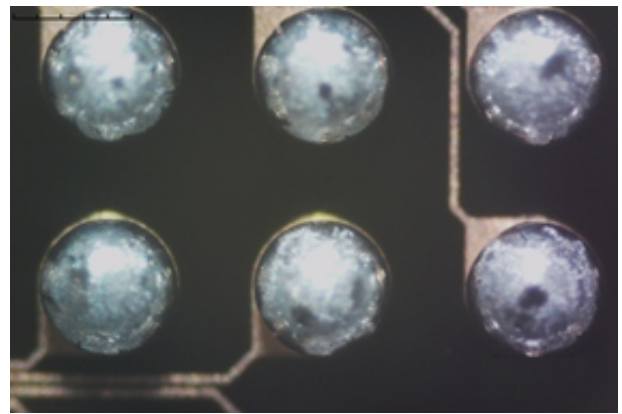


PF-709WB WAFER BUMPING PASTE FLUX

Excellent Print Stability



Excellent Cleanability



Typical Analysis

| PROPERTIES | SPECIFICATIONS | METHOD |
|---|------------------------------|--|
| Flux Classification | ORL0 | IPC-J-STD-004B |
| Appearance | Amber | Visual |
| pH - 5% Aqueous Solution | 4 - 6 | QIT |
| Halide Content | Halide - Free | IPC-TM-650 2.3.33 (Silver Chromate Test) |
| Halogen Content | Halogen - Free | EN 14582 |
| Malcom Viscosity (@10rpm) | 45 - 85 Pa.s | IPC-TM-650 2.4.34.3 (Modified) |
| Tack Strength | 100 - 200 gf | JIS Z 3284 |
| Surface Insulation Resistance (Cleaned) | > 1.0 x 10 ⁹ ohms | IPC-TM-650 2.6.3.3 |



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